

## **Amendments to the Claims**

This listing of claims will replace all prior versions, and listings of claims in the application.

### **Listing of Claims:**

Claim 1(Currently amended): A baking apparatus for use in baking semiconductor wafers, said apparatus comprising:

a chamber having an open upper part, and a hot plate disposed in said chamber and configured to support a wafer thereon;

a cover covering the upper part of said chamber and sealing said upper part, said cover having an inner surface spaced above and confronting said hot plate; and

a film extending over and integral with the inner surface of said cover which increases the rate of formation of a uniform temperature distribution in the chamber.

Claim 2(Currently amended): ~~The~~ A baking apparatus [of claim 1] for use in baking semiconductor wafers, said apparatus comprising:

a chamber having an open upper part, and a hot plate disposed in said chamber and configured to support a wafer thereon;

a cover covering the upper part of said chamber said cover having an inner surface confronting said hot plate; and

wherein said film is a film of metal extending over the inner surface of said cover, said film having a polished surface facing said hot plate, whereby the film increases the rate of formation of a uniform temperature distribution in the chamber.

Claim 3(Currently amended): The A baking apparatus of claim 1 for use in baking semiconductor wafers, said apparatus comprising:

a chamber having an open upper part, and a hot plate disposed in said chamber and configured to support a wafer thereon;

a cover covering the upper part of said chamber said cover having an inner surface confronting said hot plate; and

a wherein said film extending over the inner surface of said cover, said film comprising comprises a material selected from the group consisting of aluminum, brass, copper, gold and silver, whereby the film increases the rate of formation of a uniform temperature distribution in the chamber.

Claim 4(Original): The apparatus of claim 2, wherein said film comprises a material selected from the group consisting of aluminum, brass, copper, gold and silver.

Claim 5(Currently amended): ~~The A~~ baking apparatus of claim 1 for use in baking semiconductor wafers, said apparatus comprising:

a chamber having an open upper part, and a hot plate disposed in said chamber and configured to support a wafer thereon;

a cover covering the upper part of said chamber said cover having an inner surface confronting said hot plate; and

a ~~wherein~~ said film extending over the inner surface of said cover, said film consisting consists of material having an emissivity of 0.02 ~ 0.05, whereby the film increases the rate of formation of a uniform temperature distribution in the chamber.

Claim 6 (New): The apparatus of claim 1, wherein said film is a film of material having a polished surface facing said hot plate.

Claim 7 (New): The apparatus of claim 1, wherein said film comprises a material selected from the group consisting of aluminum, brass, copper, gold and silver.

Claim 8 (New): The apparatus of claim 6, wherein said film comprises a material selected from the group consisting of aluminum, brass, copper, gold and silver.

Claim 9 (New): The apparatus of claim 1, wherein said film consists of material having an emissivity of 0.02 ~ 0.05.